

EEC 216 Lecture #14: Temperature Measurement Circuits

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Outline

- **Announcements**
- **Review: Heat Transfer, Thermal Circuits, Thermal Design Issues**

Review: Heat Transfer Mechanisms

- **Conduction**

- Transfer medium is stationary
- Heat transfers through vibratory motion of atoms, molecules
- Ex: heat sink, thermoelectric generators

- **Convection**

- Transfer occurs through mass movement – fluid flow (liquid or gas)
- Natural: buoyancy created by temperature gradients causes fluid movement
- Forced: mass flow created by pumps or fans
- Ex: most computers use forced convection air cooling

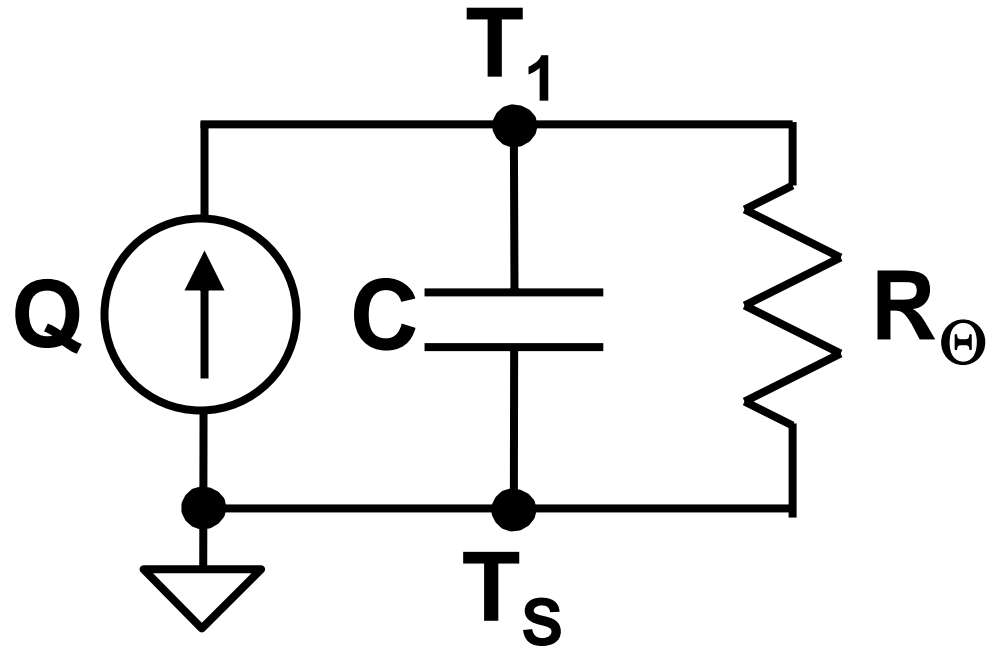
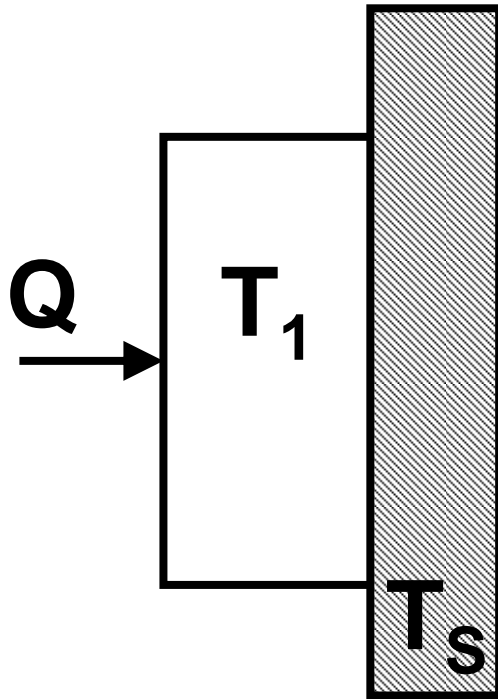
Review: Thermal Resistance

- Rate Q_{12} at which heat energy is transferred from body at temperature T_1 to temperature T_2 is linear proportional to temperature difference:

$$Q_{12} = \frac{T_1 - T_2}{R_{\ominus}}$$

- Define a thermal resistance R_{\ominus} between bodies
- Analogous to Ohm's Law: Q_{12} corresponds to current I ; T_1, T_2 corresponds to voltage V_1, V_2 ; R_{\ominus} corresponds to resistance R

Review: Thermal Circuit Example



- Mass at temperature T_1 (thermal capacitance), being supplied heat Q , in contact with sink at temperature T_s
- Final (steady-state) temperature: $T_1 = R_\Theta Q + T_s$

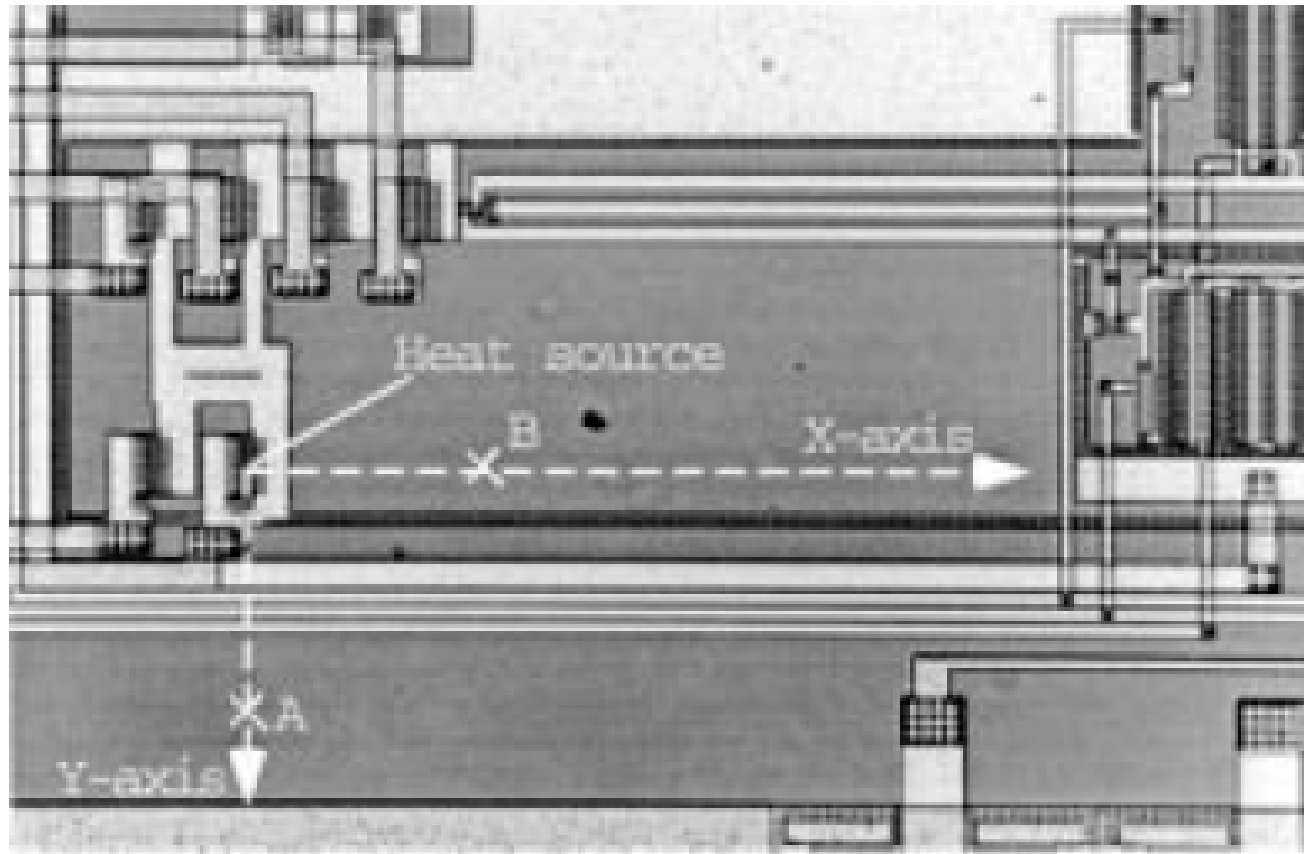
Laser Thermoreflectance Measurement

- **Thermoreflectance**: variation of the reflection coefficient of a material with temperature
- Using laser beam as light source and sensing reflected light with a photodiode, variation of diode current can be related to temperature change in illuminated area:

$$\Delta T = \psi^{-1} \frac{\Delta I}{I}$$

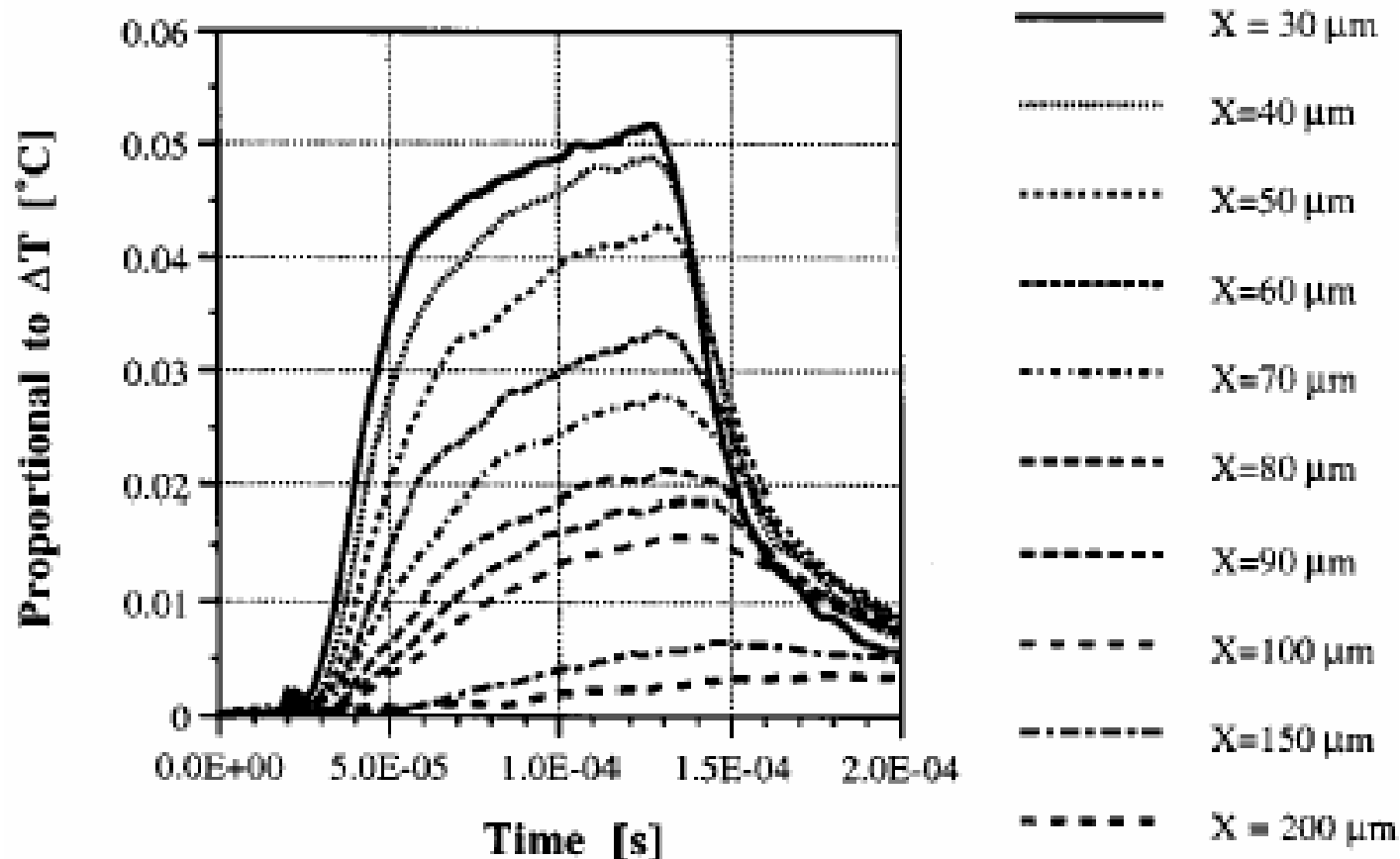
- Exact value of ψ depends on material ($1.35 \times 10^{-4} \text{ K}^{-1}$ for pure Si)
- Fast surface thermometer (dc to 10 MHz) with $1 \text{ } \mu\text{m}$ spatial resolution large dynamic range ($\Delta T = 10^{-3}$ to 10^2 K)

Heat Transfer On-Die Experiment



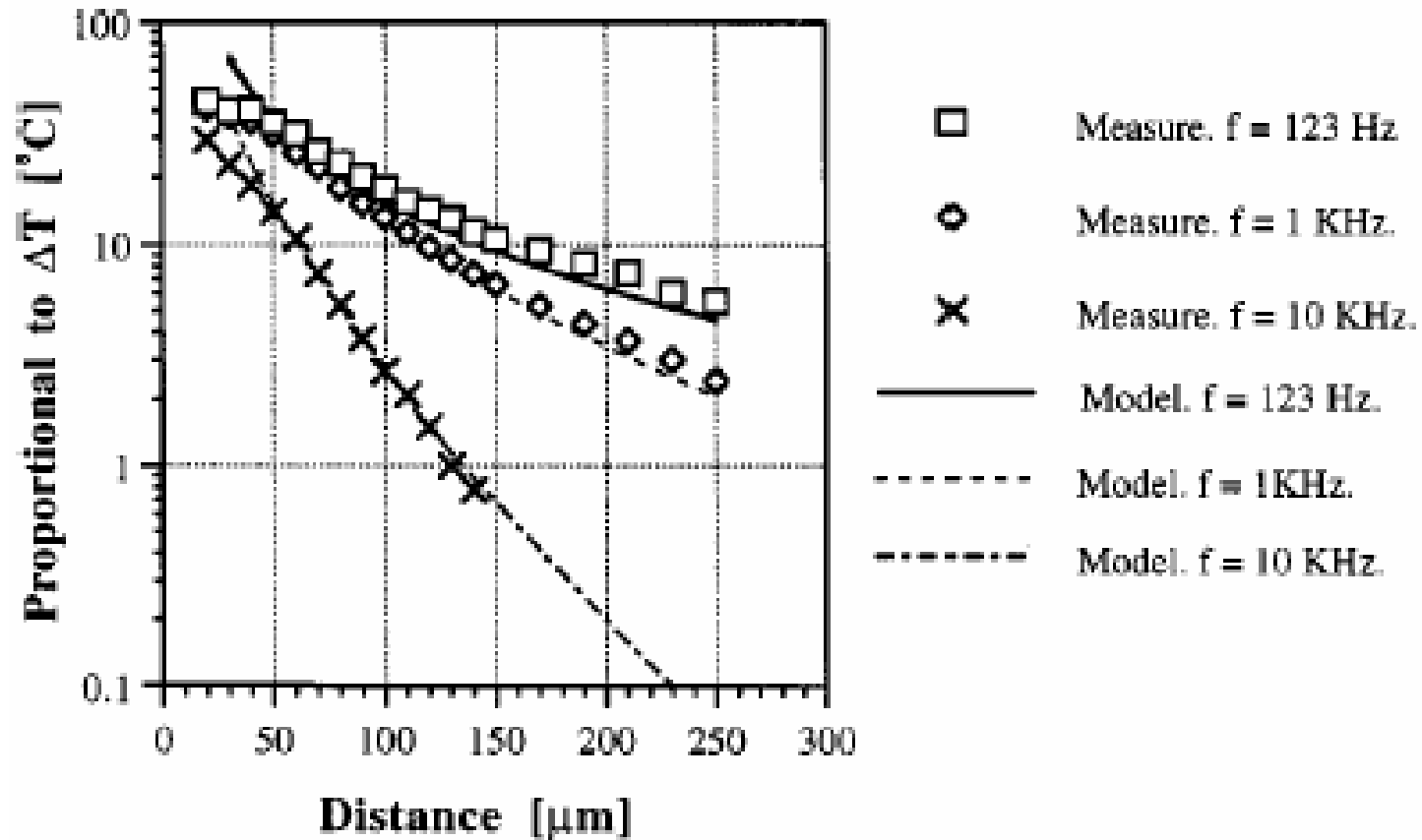
- Heat source integrated on chip
- Area with no metal, constant ψ since homogeneous thickness of passivation and oxide layers

Thermoreflectance Experiment Results



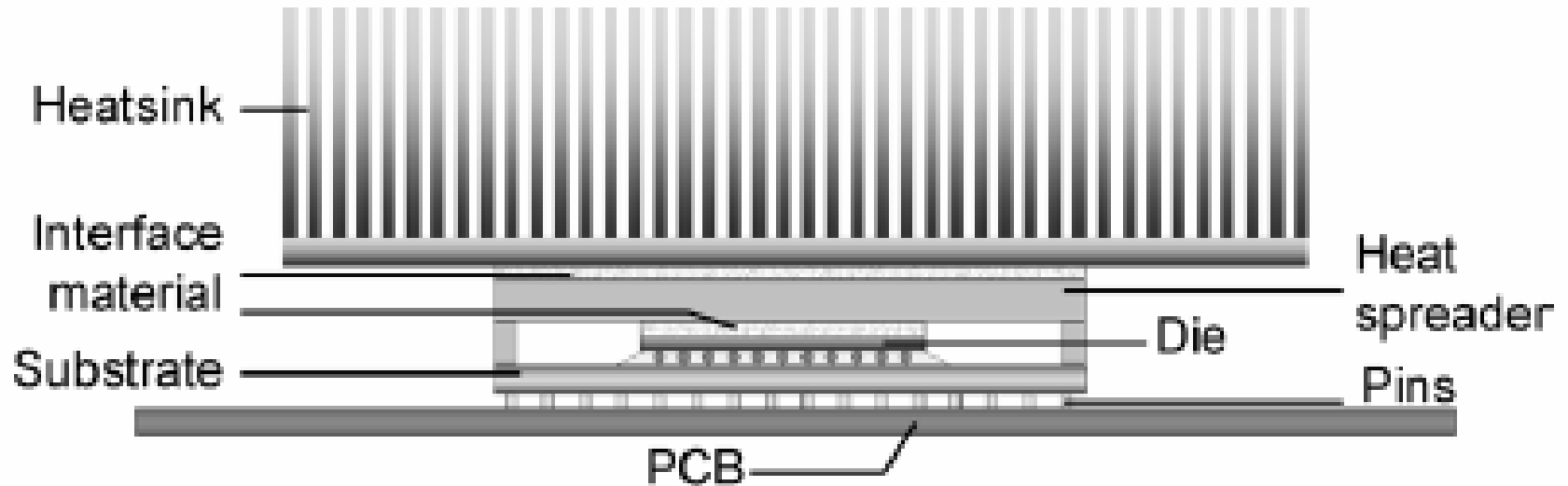
- Heat source activated at 23 mW for 100 μs
- ΔT plotted along x-axis defined above
- Temperature wave diffuses as if along *RC* ladder

Theory Agreement with Experiment Results



- Temperature wave amplitude as function of distance, for different heat source frequencies
- Calculated using diffusion equation (*RC* network limit)

Review: Typical Microprocessor Package

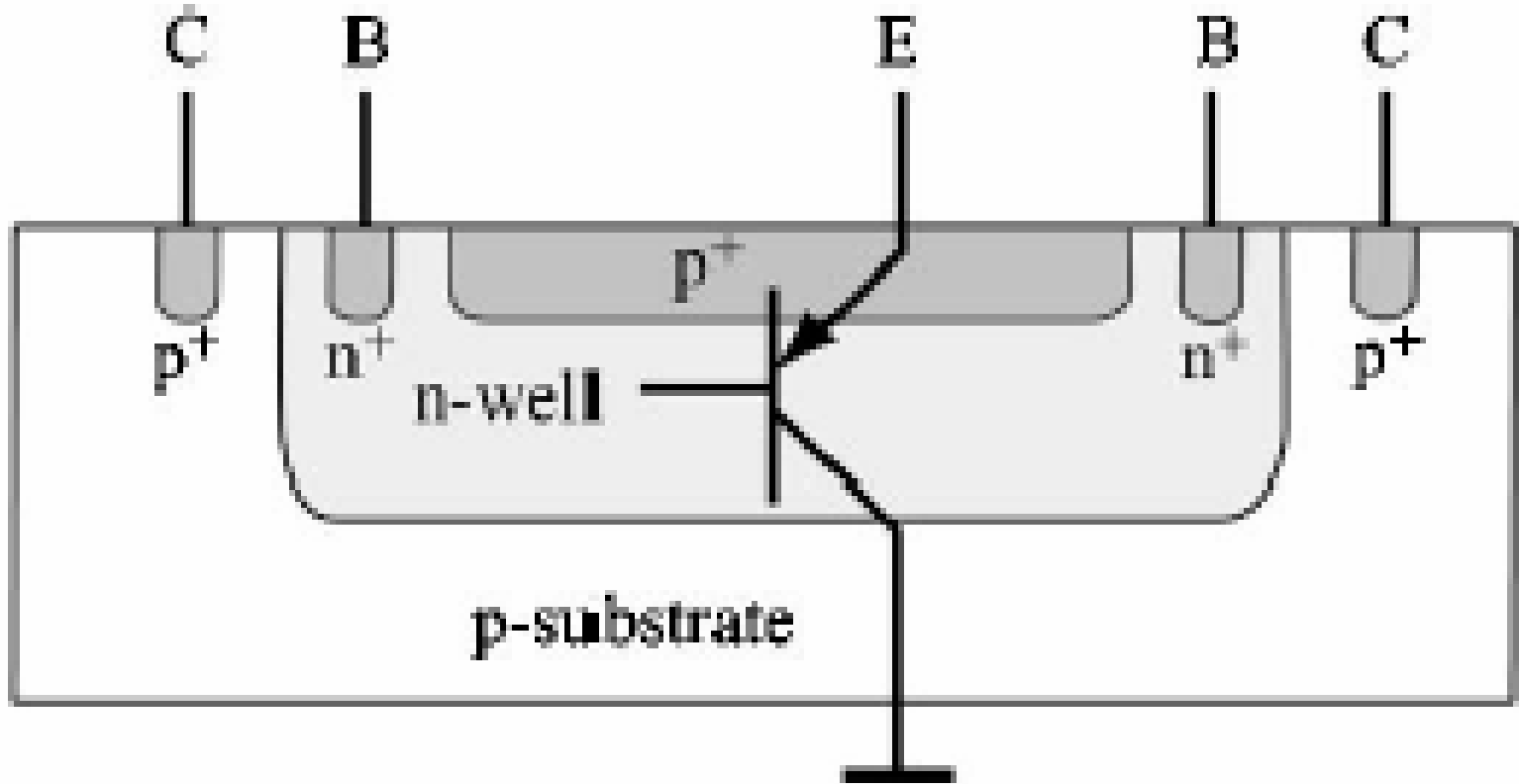


- Heat spreader expands thermal interface between die and heat sink plate (die back side)
- Thermal conduction through flip-chip bumps and package solder balls into PCB (another heat sink) on die front side
- Two paths with thermal resistances in parallel, back side of die path more efficient

Principles of Temperature Measurement

- **Bipolar devices can be used for temperature sensing in CMOS technology**
 - Lateral BJT: current flow parallel to substrate
 - Substrate BJT: current flow into substrate
 - Substrate devices have more ideal behavior, less sensitive to mechanical stress
- **In typical n-well CMOS process, form substrate pnp transistor by p⁺ source/drain diffusion in n-well**
 - Collector formed by substrate
- **Main disadvantages: substrate usually grounded, low current gain (around 10)**
 - OK for temperature sensing applications

Substrate PNP Transistor



- Disadvantages can be relieved by BiCMOS process with explicit bipolar devices

Temperature Measurement Approach

- Use BJT base-emitter voltage (V_{BE}) as temperature measurement
- Transistor biased in forward-active has exponential dependence of collector current I_C on V_{BE} :

$$I_C(T) = I_S(T) \exp\left(\frac{qV_{BE}}{kT}\right)$$

- k is Boltzmann's constant, q the electron charge, and I_S the transistor saturation current

I_S Temperature Dependence

$$I_C(T) = A_E C T^\eta \exp\left(\frac{q(V_{BE} - V_{g0})}{kT}\right)$$

- A_E : emitter area
- C and η : process-dependent constants
- V_{g0} : bandgap voltage extrapolated to 0 K

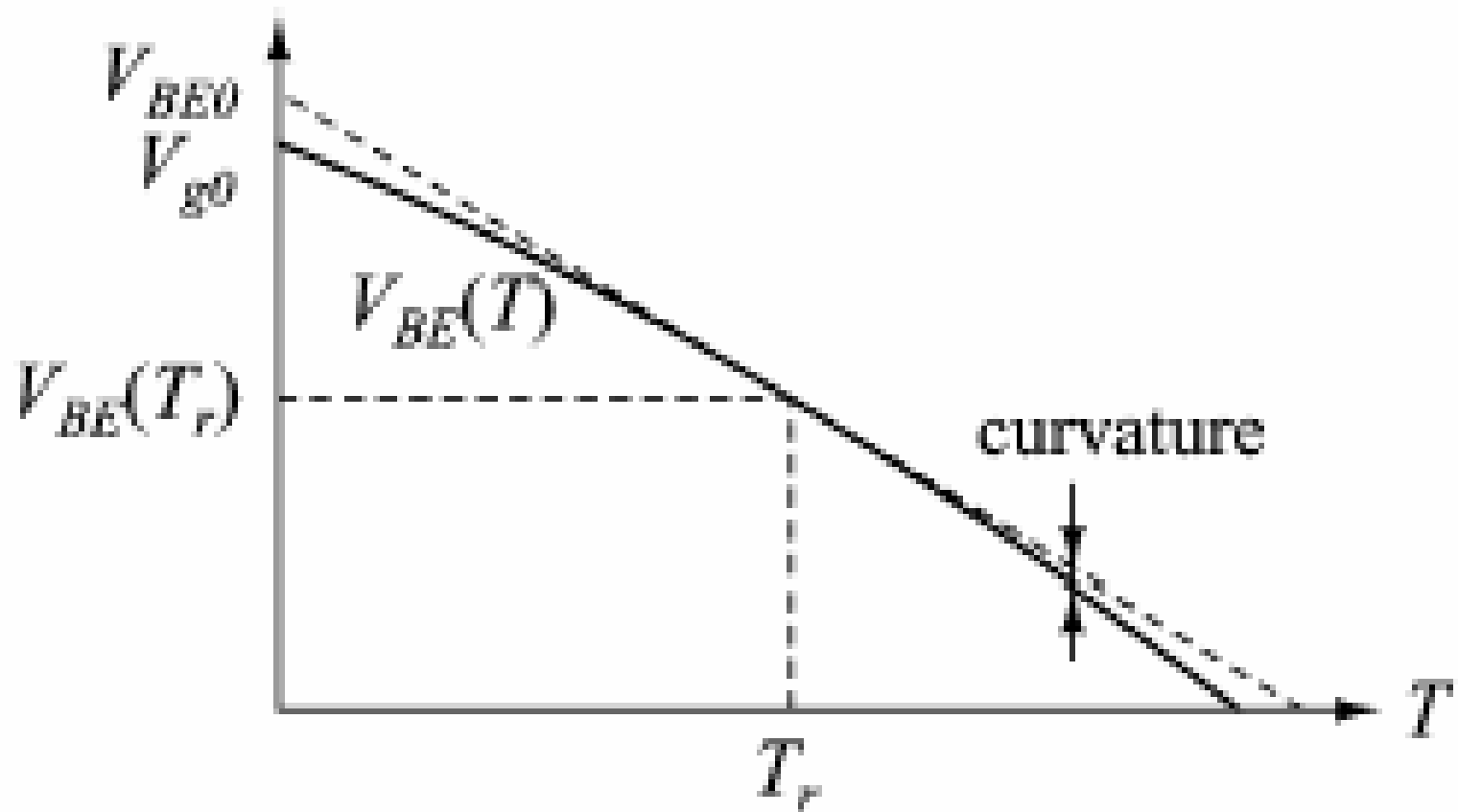
Base-Emitter Voltage vs. Collector Current

$$V_{BE}(T) = V_{g0} \left(1 - \frac{T}{T_r} \right) + \frac{T}{T_r} V_{BE}(T_r) - \eta \frac{kT}{q} \ln \left(\frac{T}{T_r} \right) + \frac{kT}{q} \ln \left(\frac{I_C(T)}{I_C(T_r)} \right)$$

- T_r and $V_{BE}(T_r)$ are a reference temperature and the base-emitter voltage at that temperature:

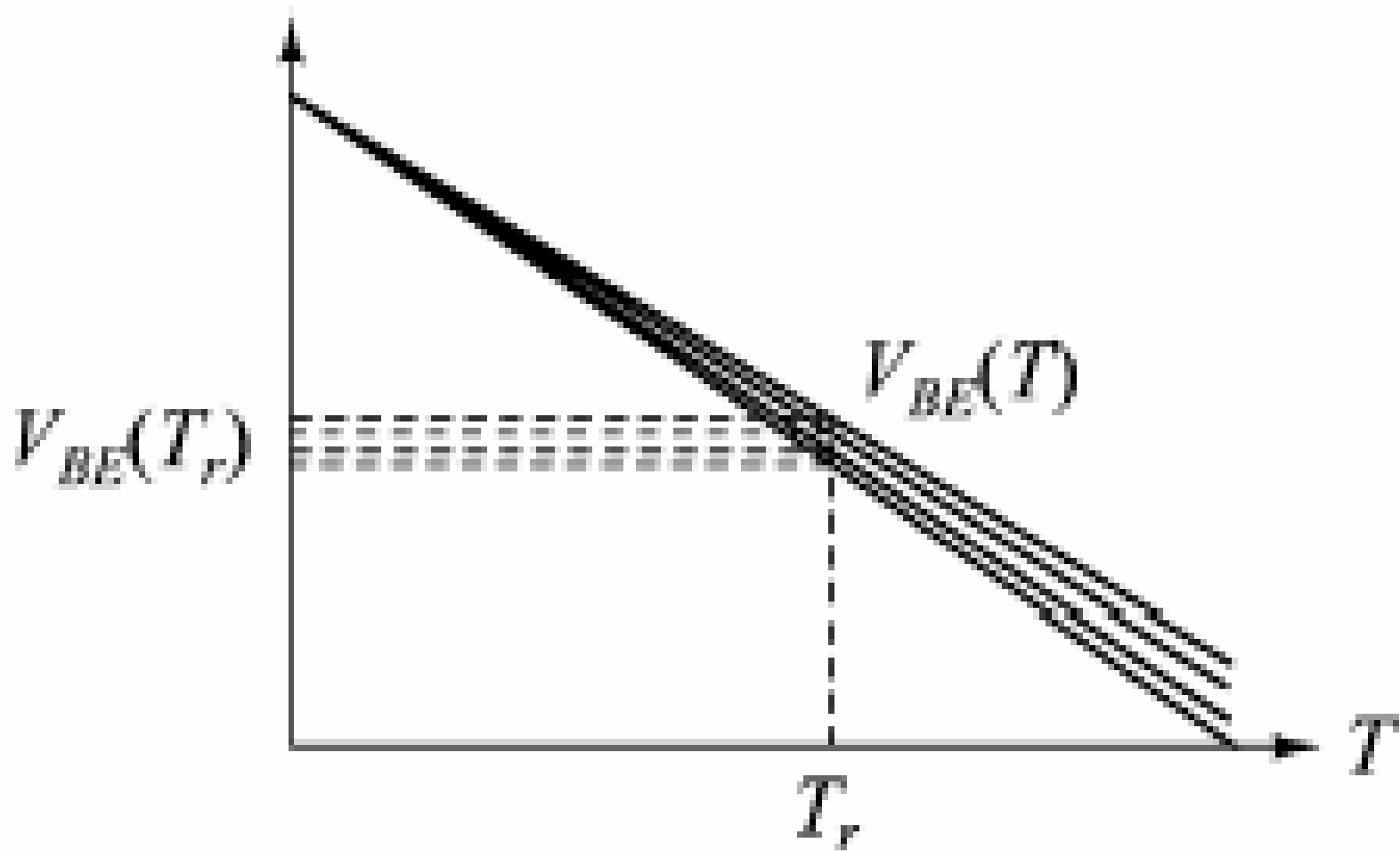
$$V_{BE}(T_r) = V_{g0} + \frac{kT_r}{q} \ln \left(\frac{I_C(T_r)}{A_E C T_r^\eta} \right)$$

Temperature Dependence of V_{BE}



- Almost linear dependence with sensitivity about -2 mV/K
- Curvature nonlinearity can be compensated (see bandgap reference circuits)

Sensitivity Variation Due to Process



- Since $V_{BE}(T_r)$ process dependent, sensitivity also process dependent

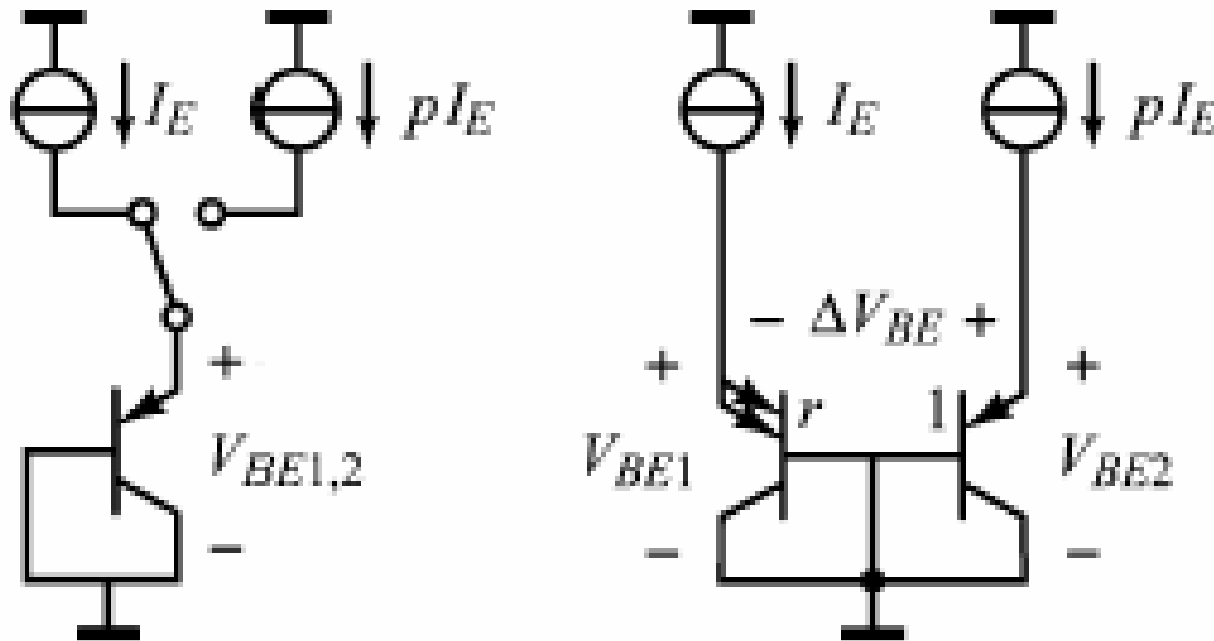
ΔV_{BE} Temperature Measurement

- Eliminate process dependence by using differential measurement
- Measure ΔV_{BE} between base-emitter voltages of a transistor operated at two current densities I_{C1} and I_{C2} :

$$\Delta V_{BE} = V_{BE1} - V_{BE2} = \frac{kT}{q} \ln \left(\frac{I_{C2}}{I_{C1}} \right)$$

- For constant collector current ratio, ΔV_{BE} is PTAT

ΔV_{BE} Measurement Circuits

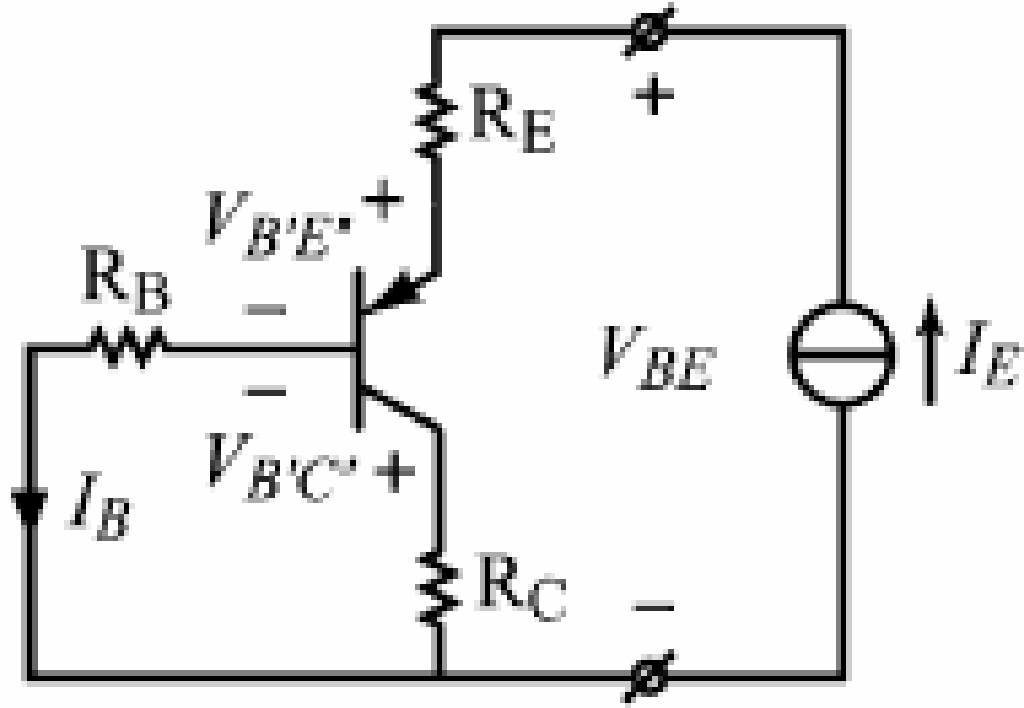


- **Single diode-connected substrate pnp with switched current sources with ratio p**
- **Two diode-connected substrate pnp's with current ratio p and emitter area ratio r**

Measurement Nonidealities

- **Proper matching required to ensure accuracy**
 - E.g., ratio of emitter areas set by parallel combination of identical unit transistors
- **Typical value of pr ratio is 10**
 - Results in sensitivity of ΔV_{BE} around $200 \mu\text{V/K}$
 - Small sensitivity requires offset-cancellation in readout circuitry, A/D converter
- **Assuming good matching, accuracy then limited by pnp transistor nonidealities**
 - Ex: Series resistance, current-gain variation, high-level injection, Early effect (base width modulation)
 - Look at series resistance example

Substrate PNP With Parasitic Resistances



- Voltage drop across base and emitter resistances is added to V_{BE} measured externally
- Results in an offset to PTAT temperature dependence of V_{BE}

ΔV_{BE} With Series Resistance

$$\Delta V_{BE} = (I_{B1} - I_{B2})R_S + \frac{kT}{q} \ln\left(\frac{I_{C2}}{I_{C1}}\right)$$

- **Series resistance $R_S = R_B + R_E(\beta_F + 1)$, where β_F is the transistor current gain in forward active regime**
- **For typical values, this results in a temperature offset of about 0.64 °C**
- **Offset can be eliminated by measuring V_{BE} at three transistor bias currents**

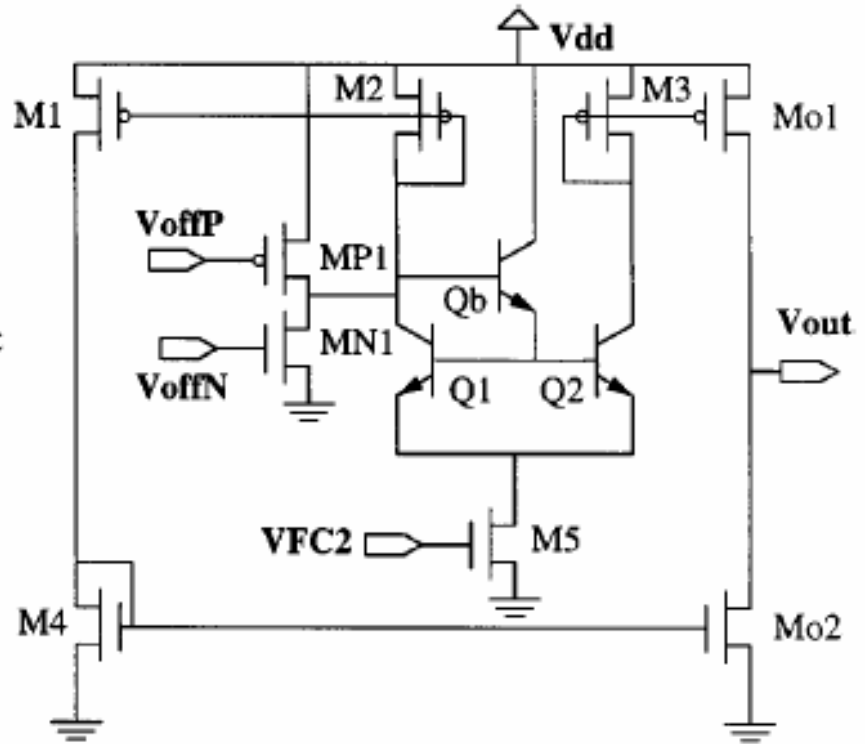
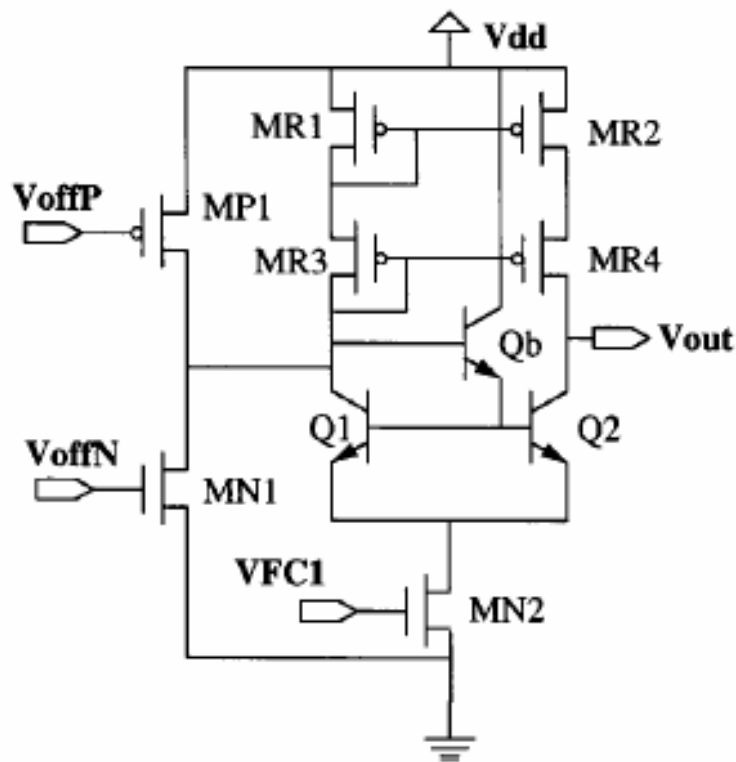
ΔV_{BE} With Three Bias Currents

$$\Delta V_{BE12} = (I_{B1} - I_{B2})R_S + \frac{kT}{q} \ln\left(\frac{I_{C2}}{I_{C1}}\right)$$

$$\Delta V_{BE32} = (I_{B3} - I_{B2})R_S + \frac{kT}{q} \ln\left(\frac{I_{C3}}{I_{C2}}\right)$$

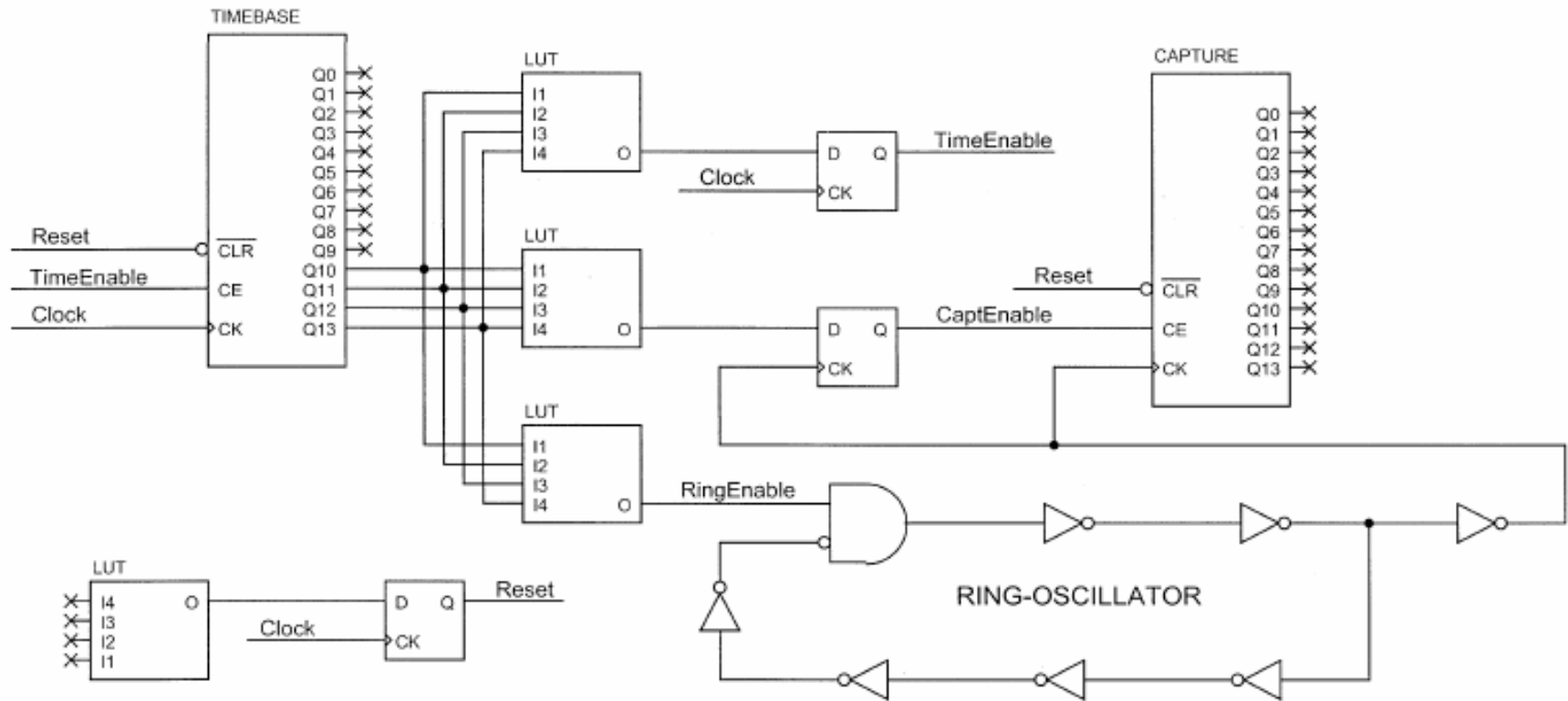
- **Two equations in two unknowns can be solved for R_S and T**
- **Must ensure matching among three biases**

BiCMOS Differential Temperature Sensor



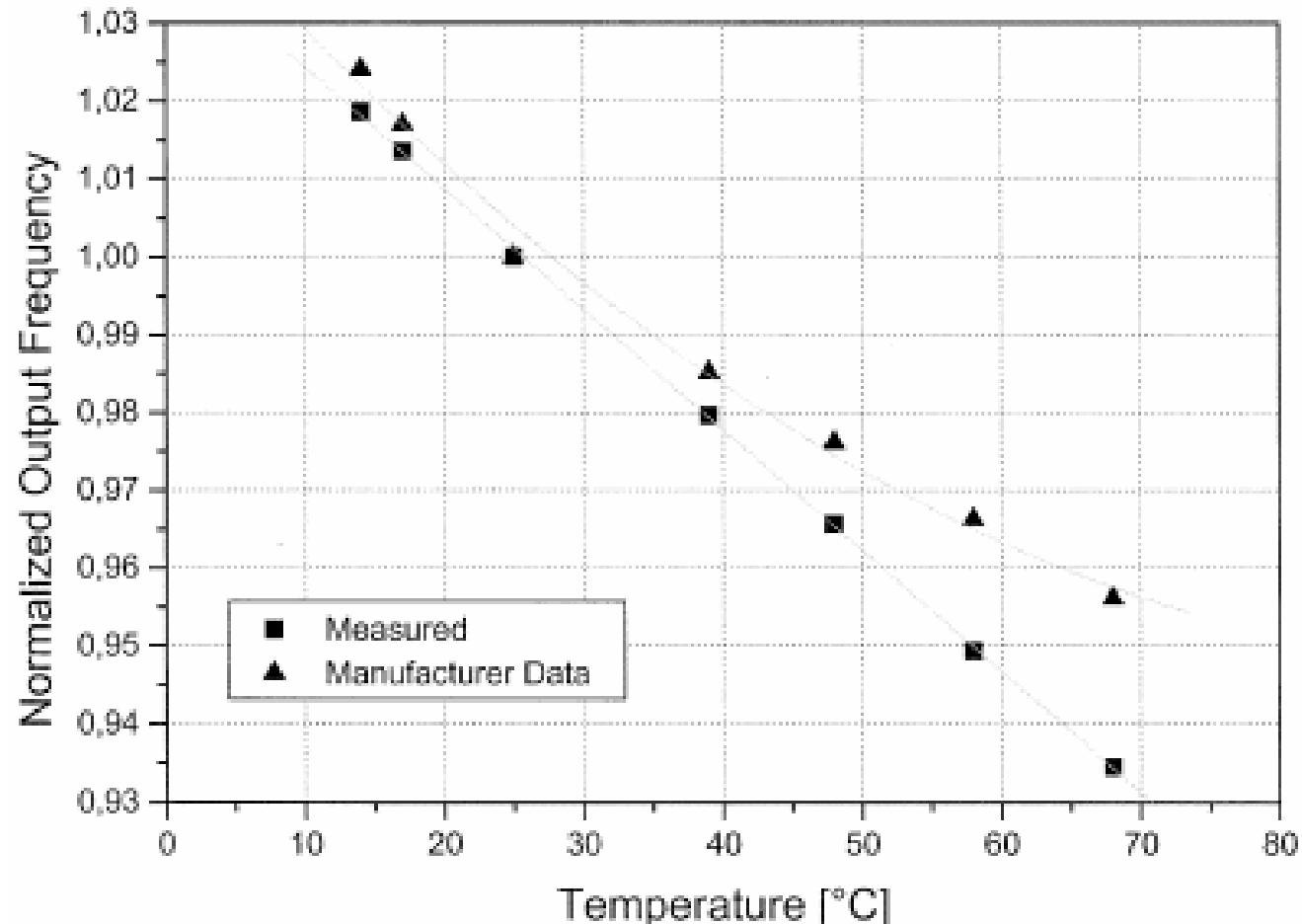
- Two examples use explicit NPN devices in BiCMOS process
- Better current gain and freedom of collector bias

Digital Temperature Measurement Circuit



- Temperature affects ring oscillator frequency and final counter value when enabled for fixed duration
- Implemented on FPGA to find hot spots

Frequency vs. Temperature Dependence



- Frequency varies slowly with temperature, must ensure counter difference is detectable

Conclusions

- **Temperature measurement important for system power management**
 - Monitor local heating to control clock gating, power supply voltage scaling
 - Helps reliability as well as power reduction
- **Analog circuits rely on temperature dependence of bipolar base-emitter voltages at constant current**
 - Highly accurate measurements even with poor bipolar performance (e.g., substrate pnp transistors in CMOS)
 - Use many analog compensation techniques to improve accuracy, eliminate transistor nonidealities
- **Digital circuits also possible but limited in accuracy**